

Inventor: Shen Buswell et al
 Title: Methods and systems for a forming slots in
 a semiconductor substrate containing . . .

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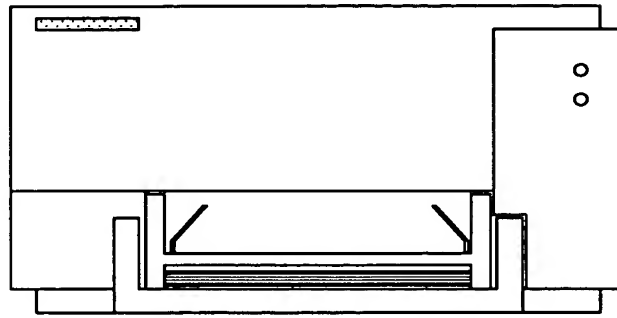


Fig.1

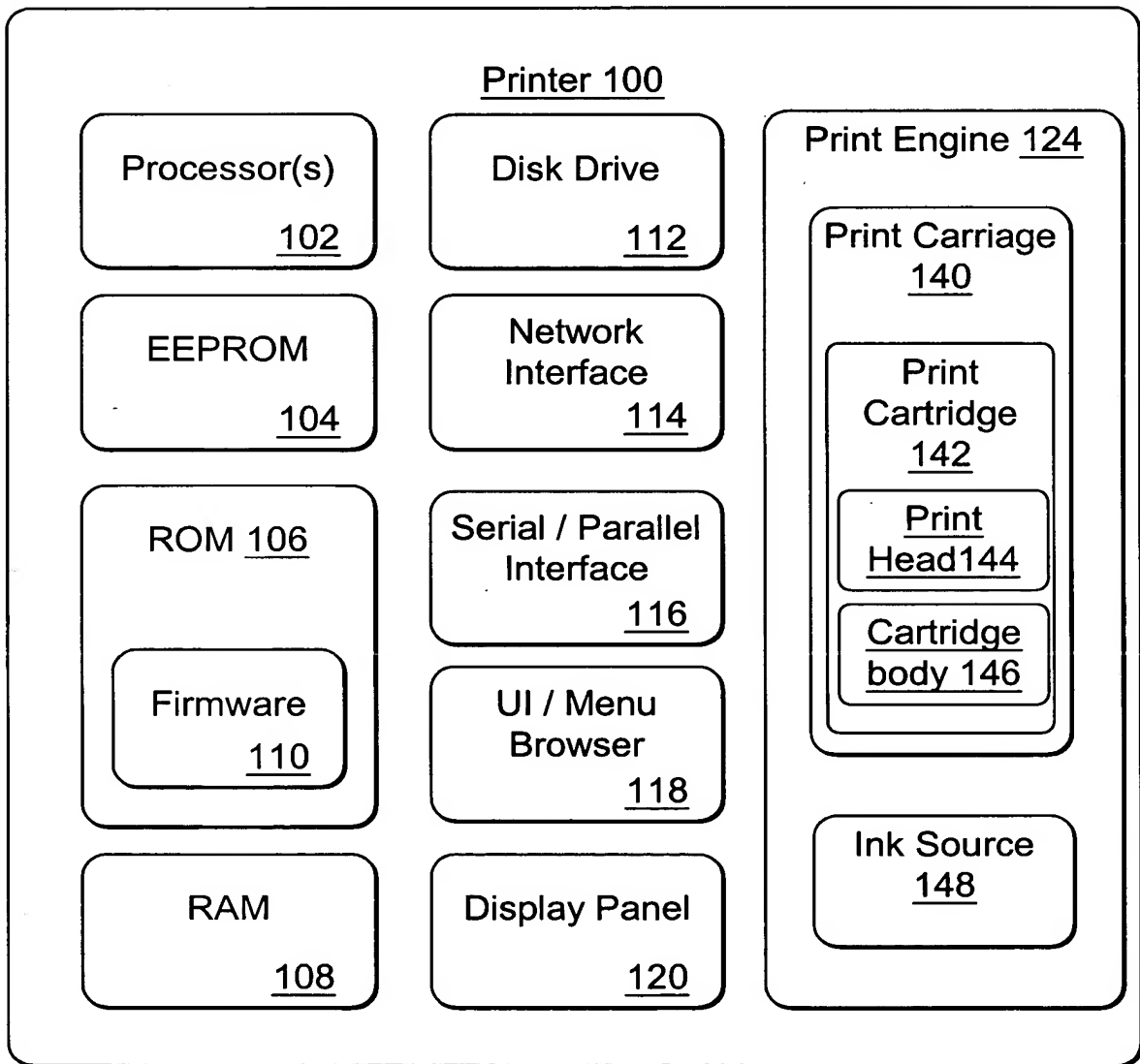


Fig. 2

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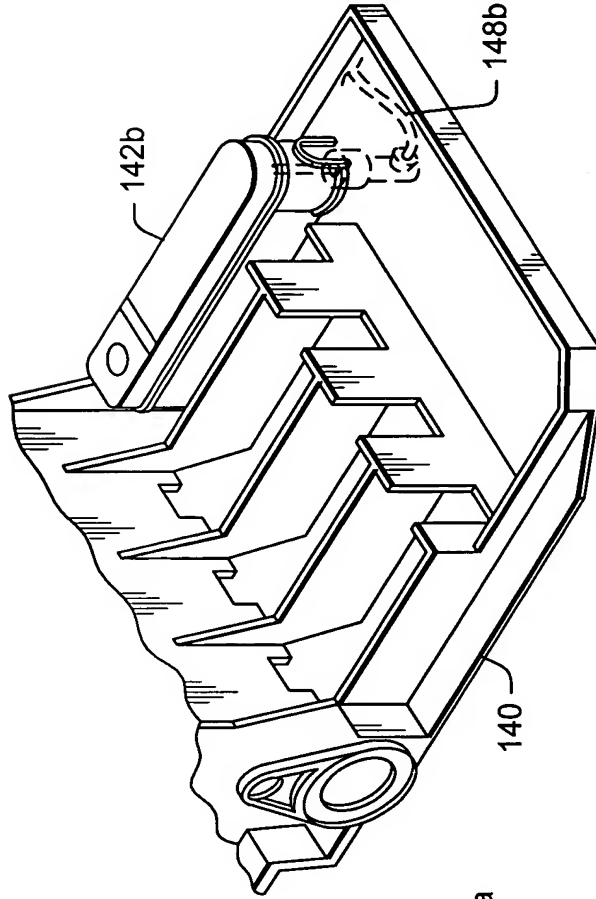


FIG. 3

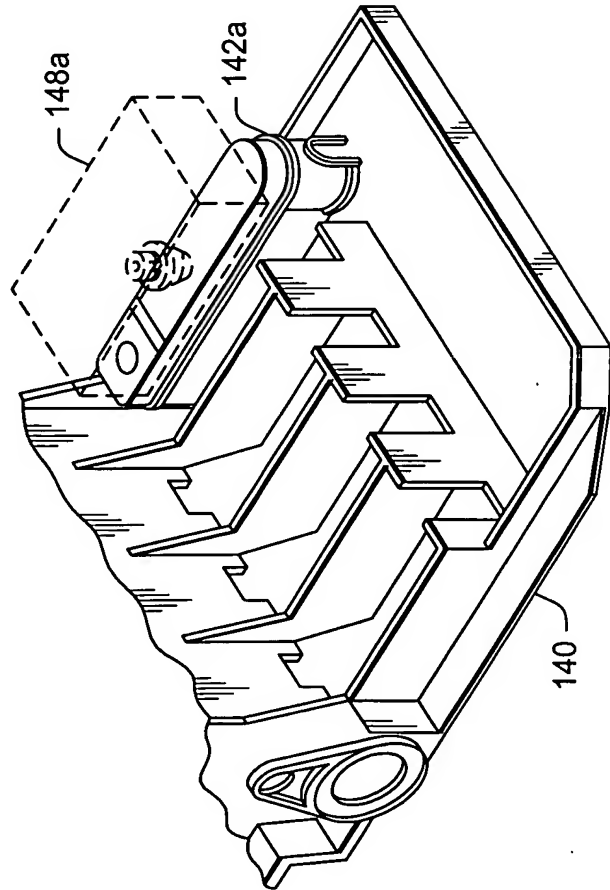


FIG. 4

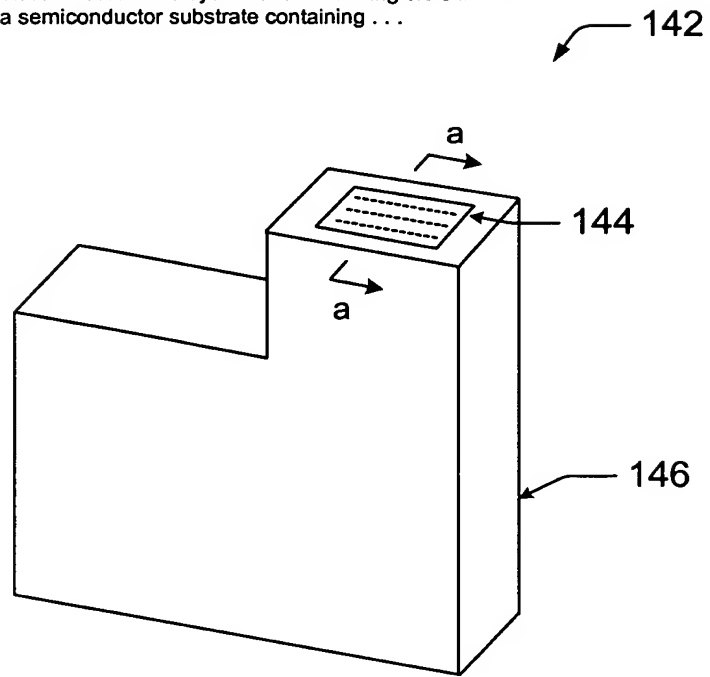


Fig. 5

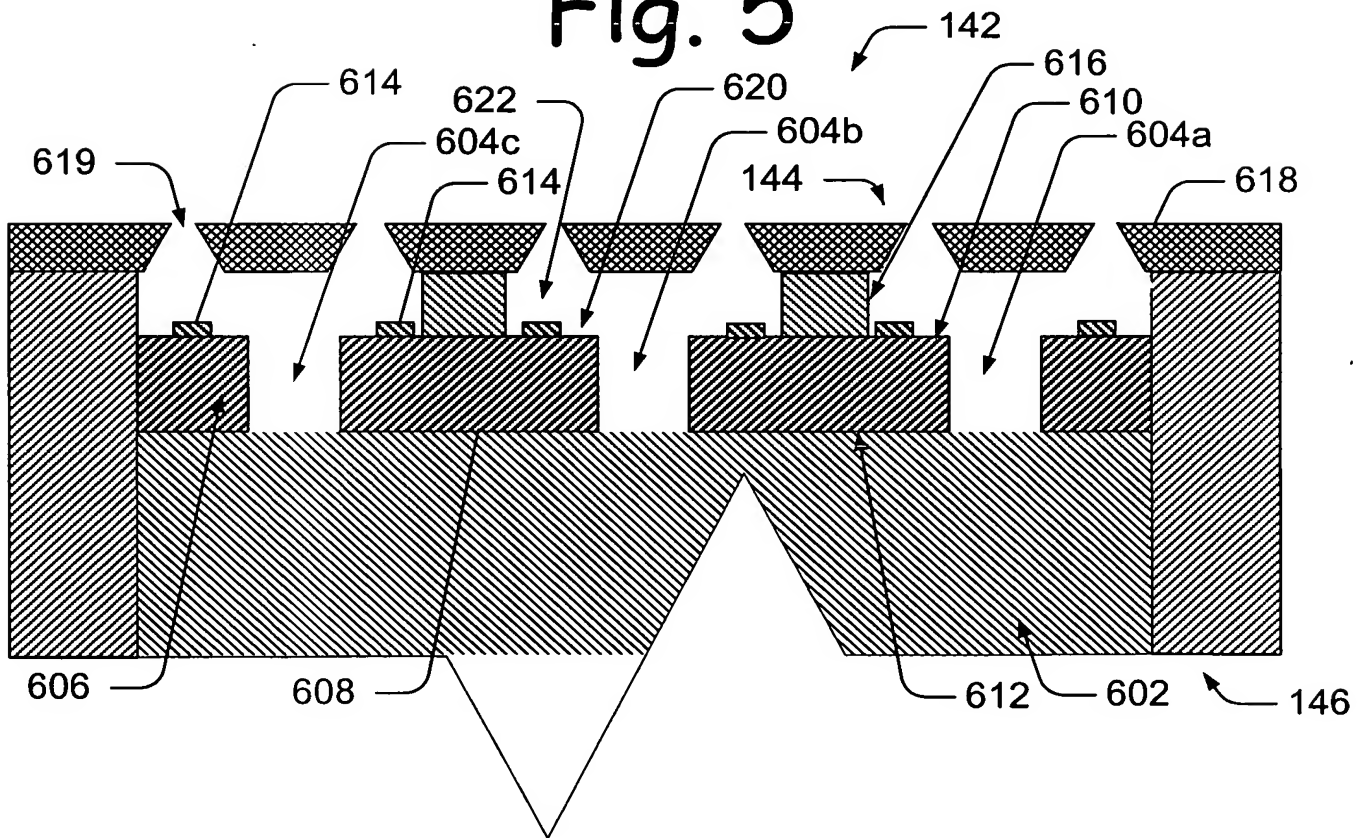


Fig. 6

10061492.013102

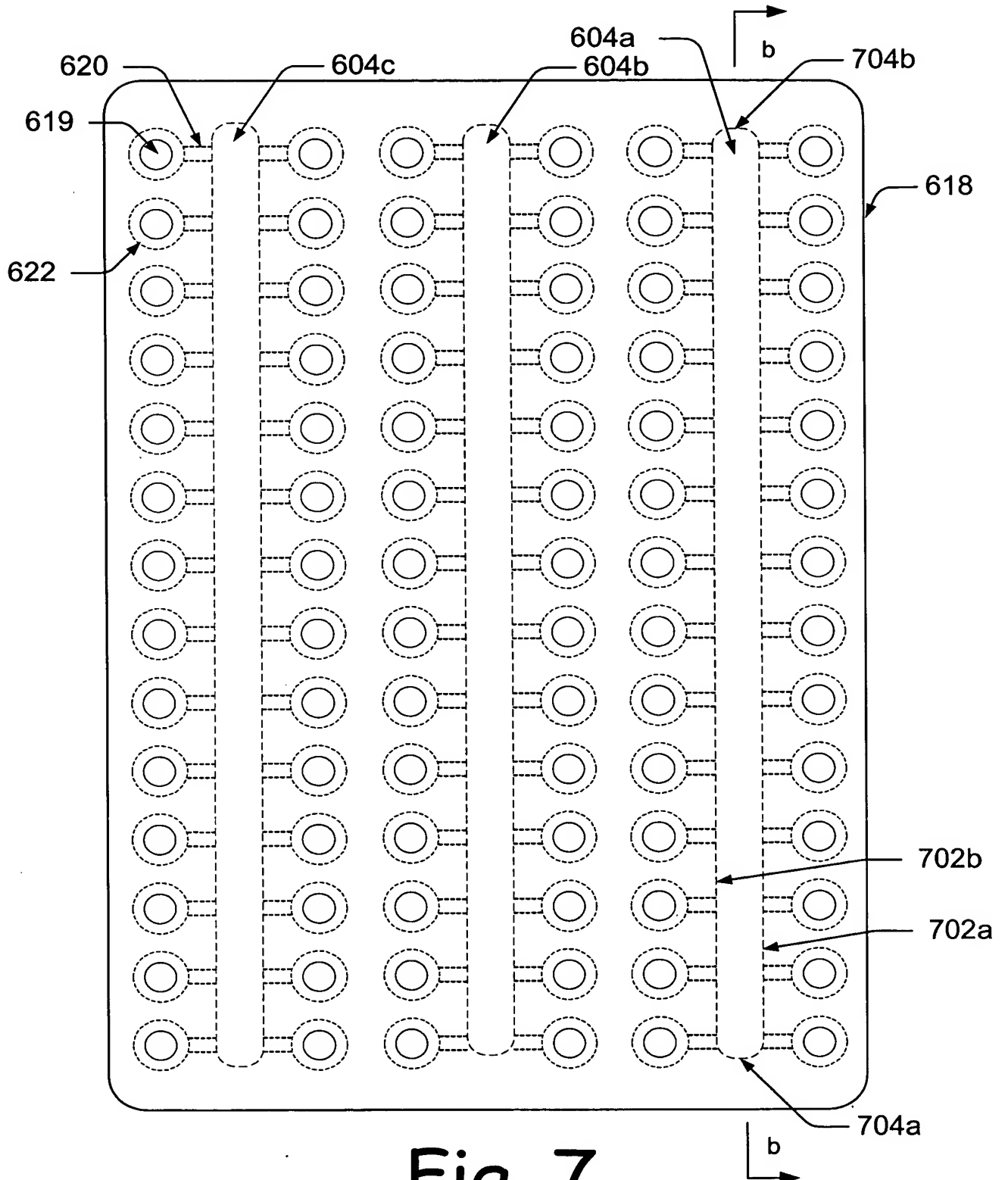


Fig. 7

2016012649001

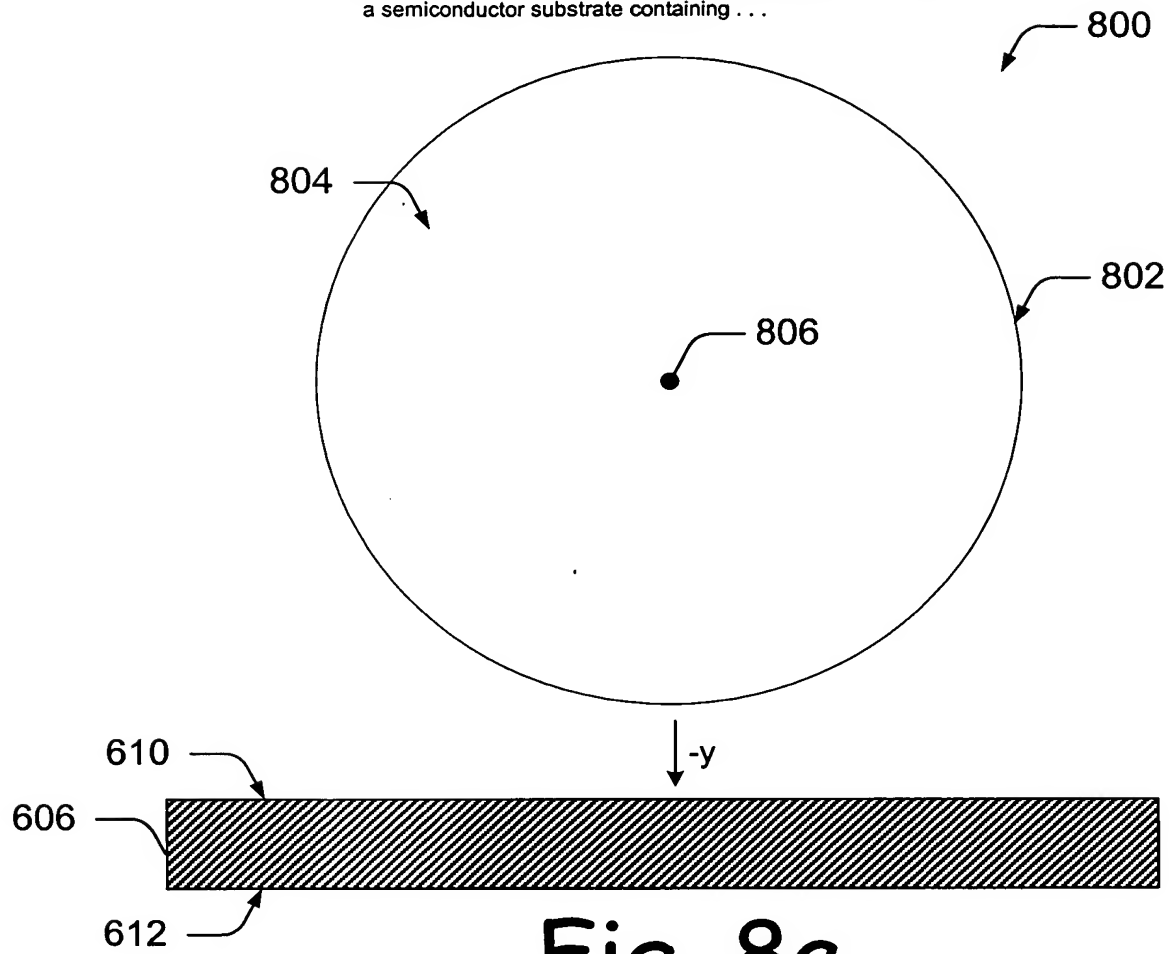


Fig. 8a

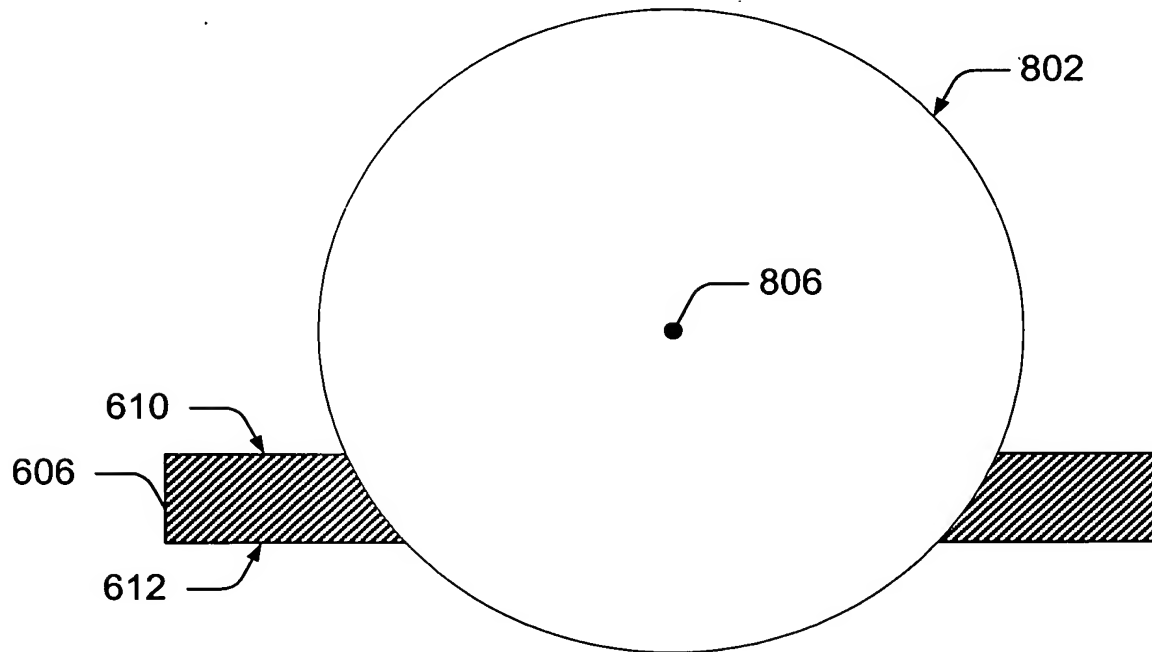


Fig. 8b

201601492.013101

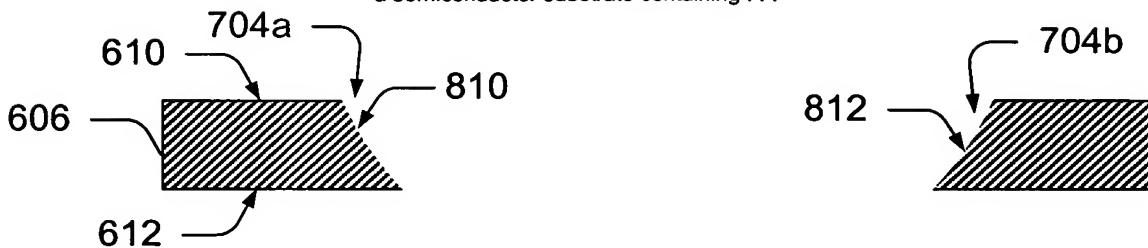


Fig. 8c

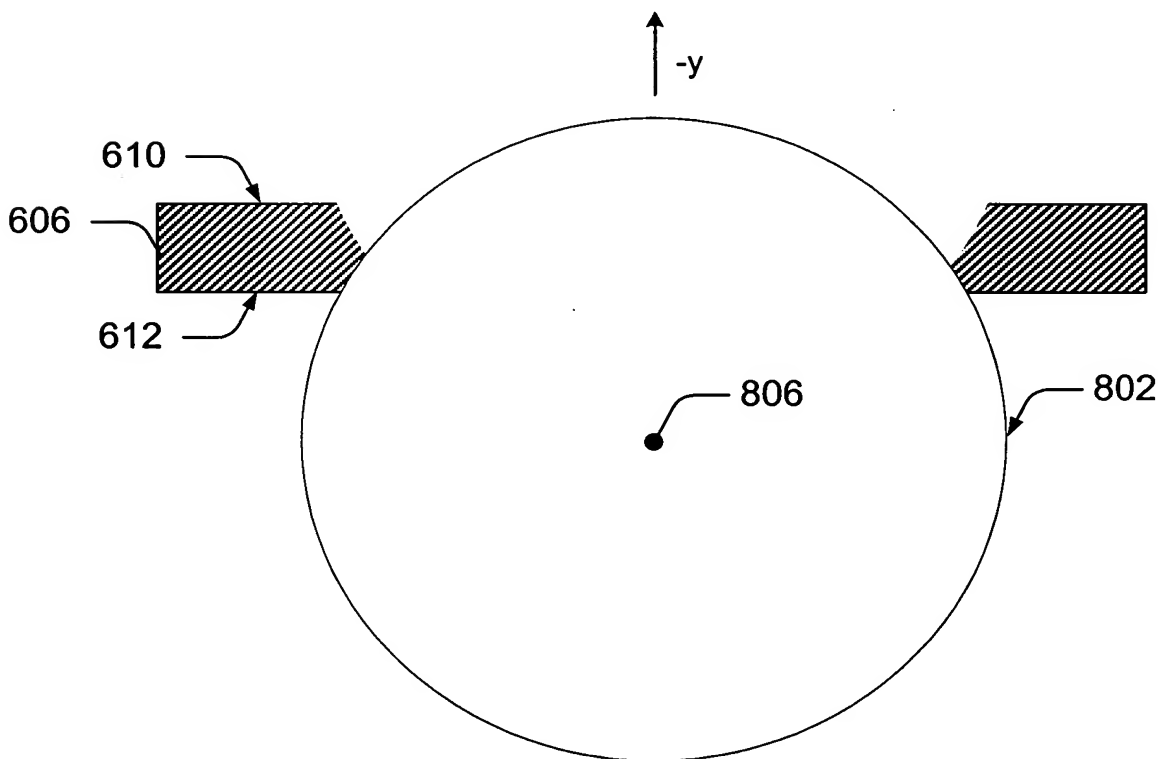


Fig. 8d

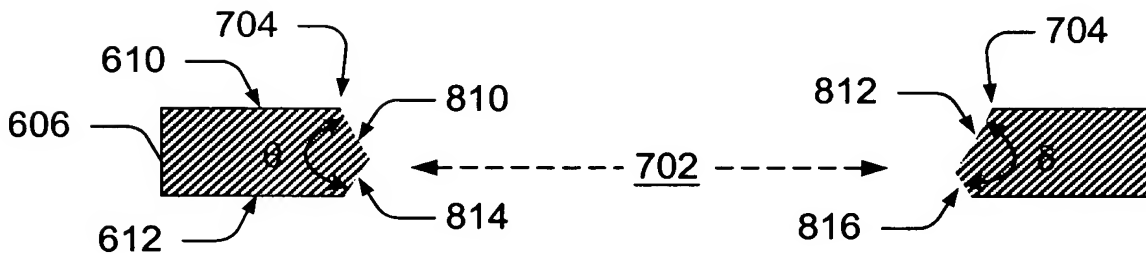
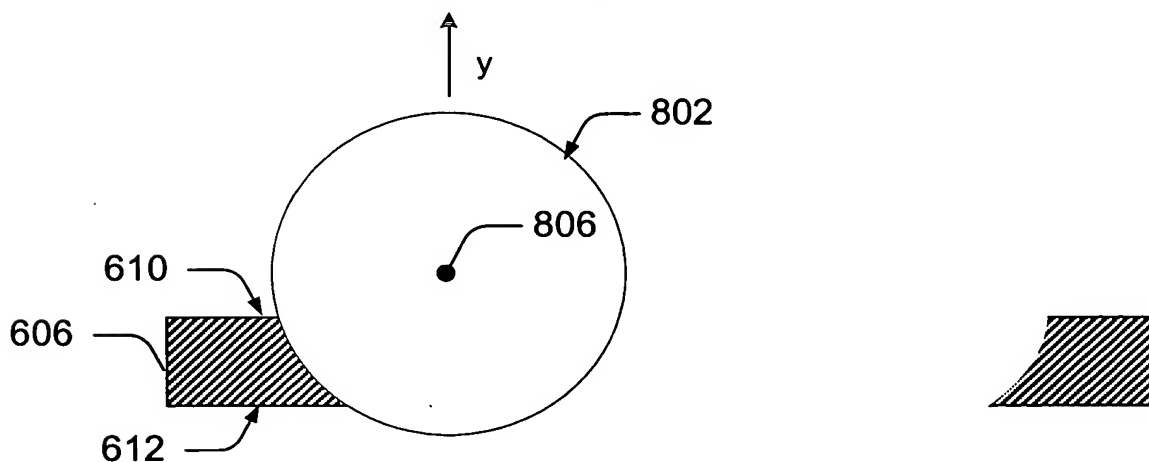
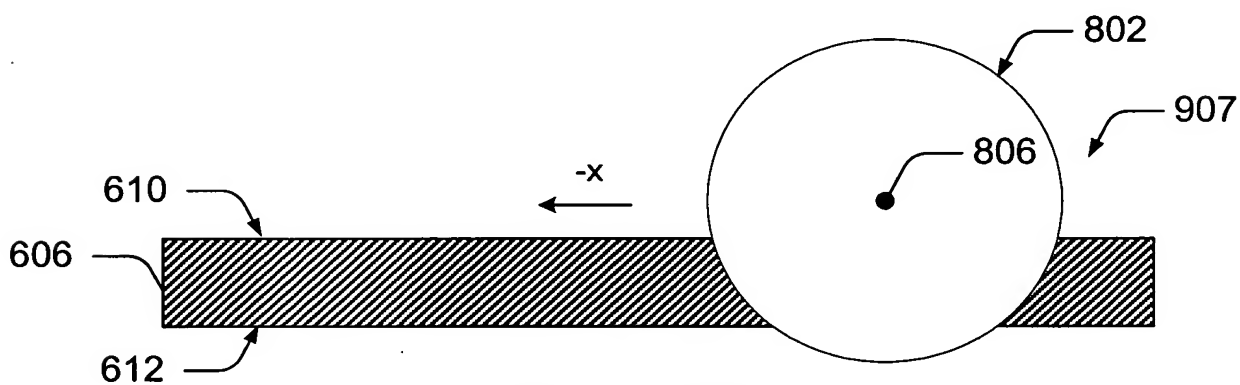
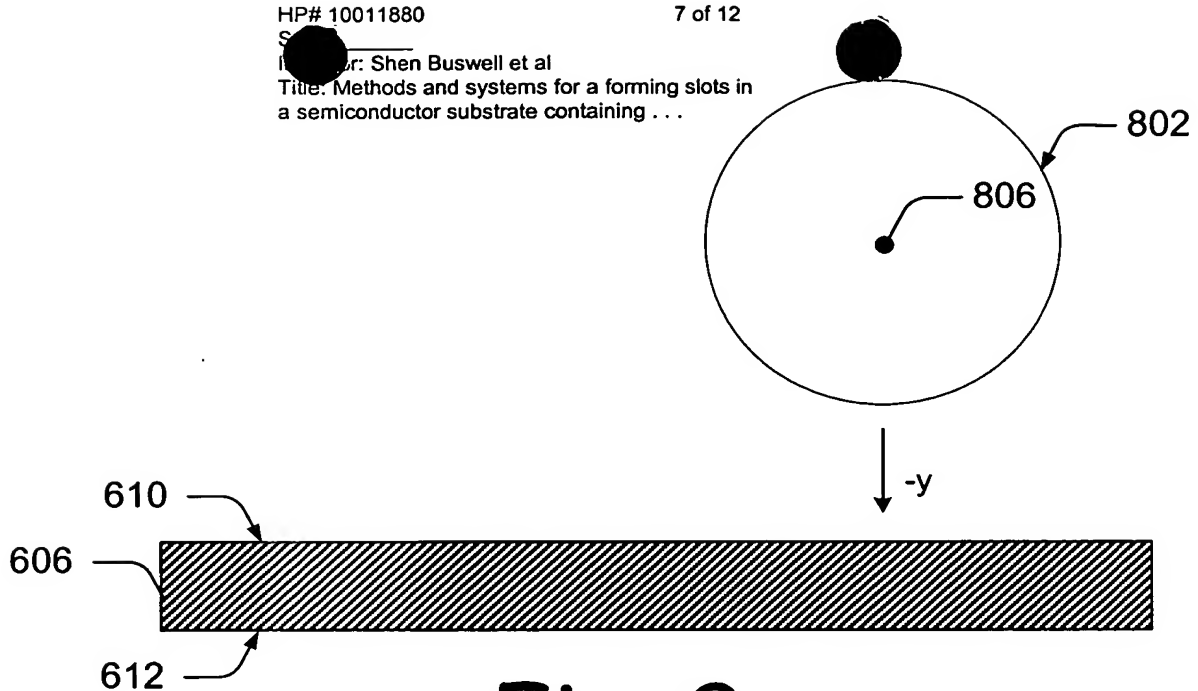


Fig. 8e

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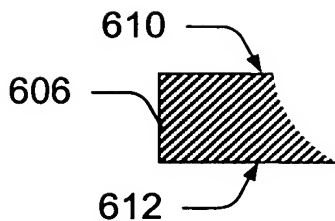


Fig. 9d

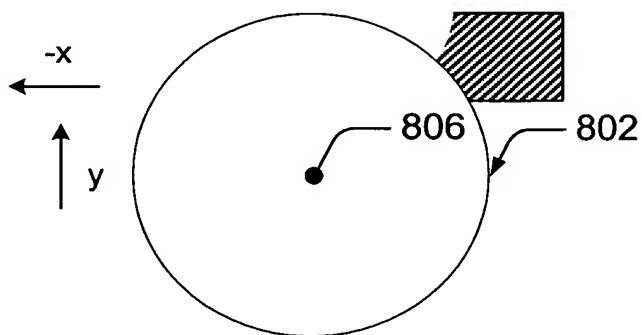
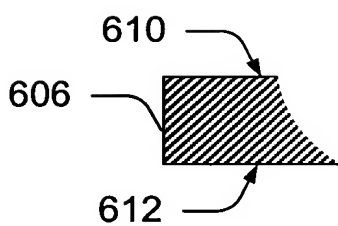


Fig. 9e

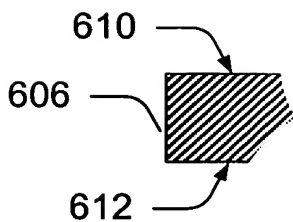


Fig. 9f

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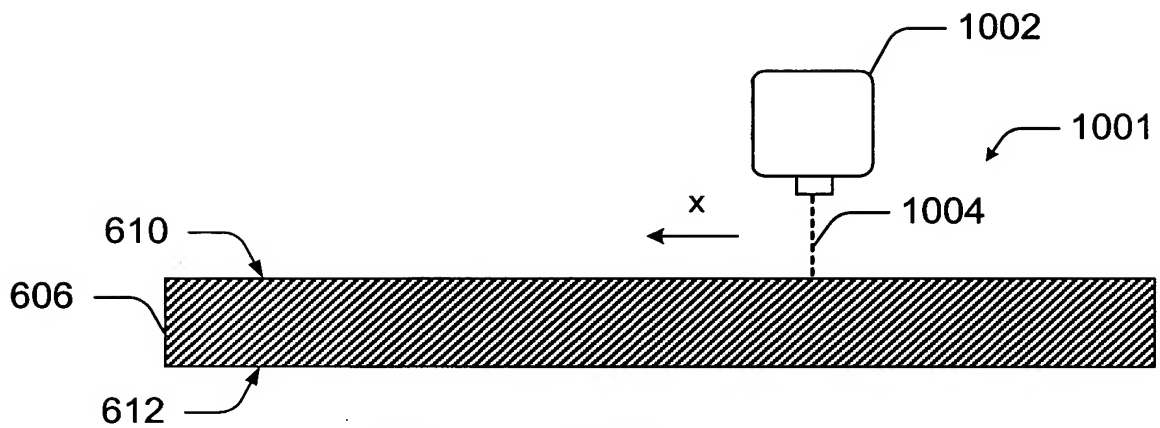


Fig. 10a

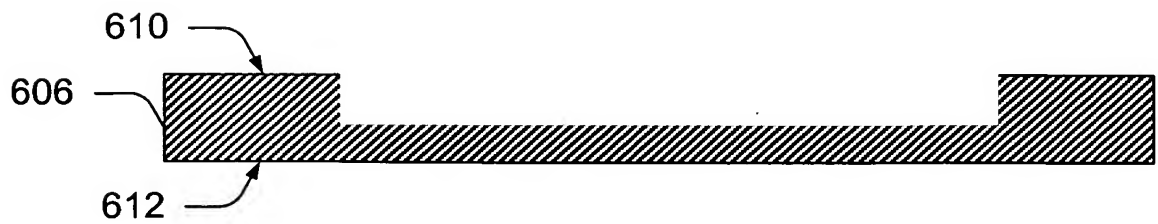


Fig. 10b

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201610" 25419001

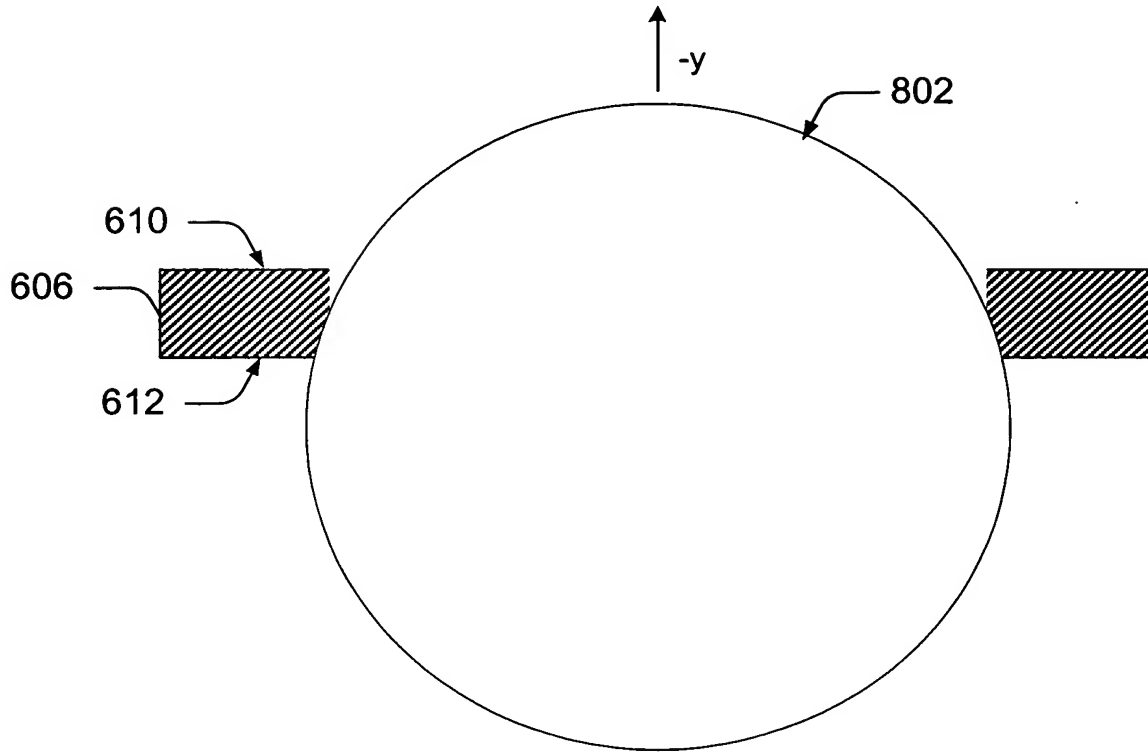


Fig. 10c

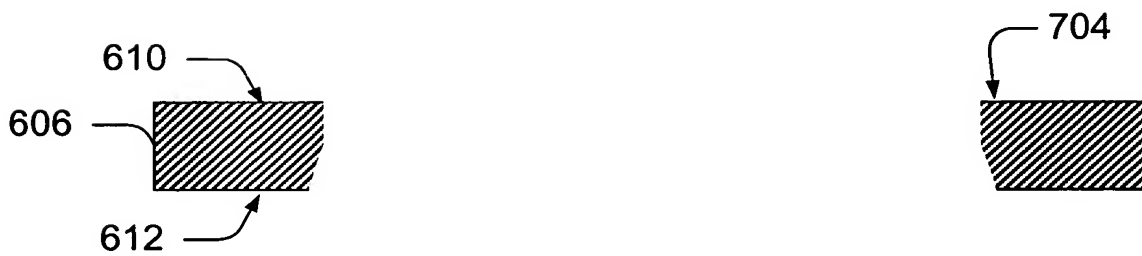


Fig. 10d

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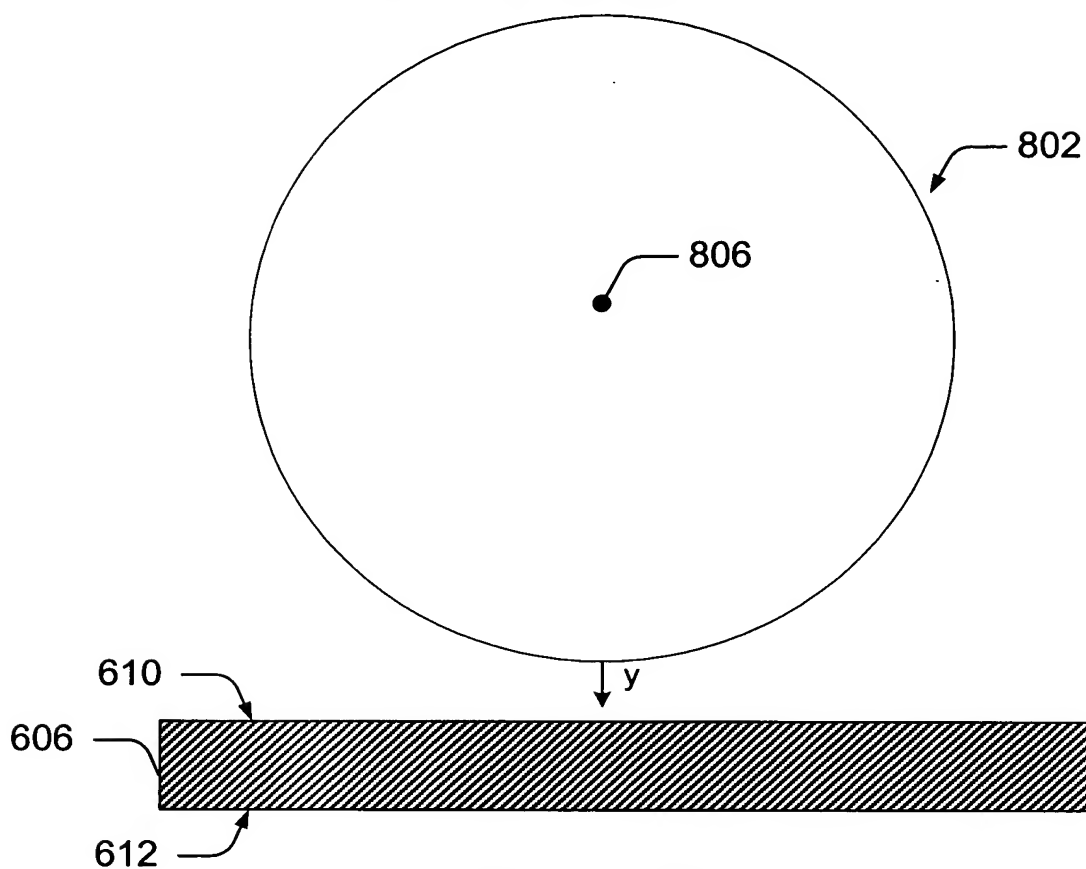


Fig. 11a

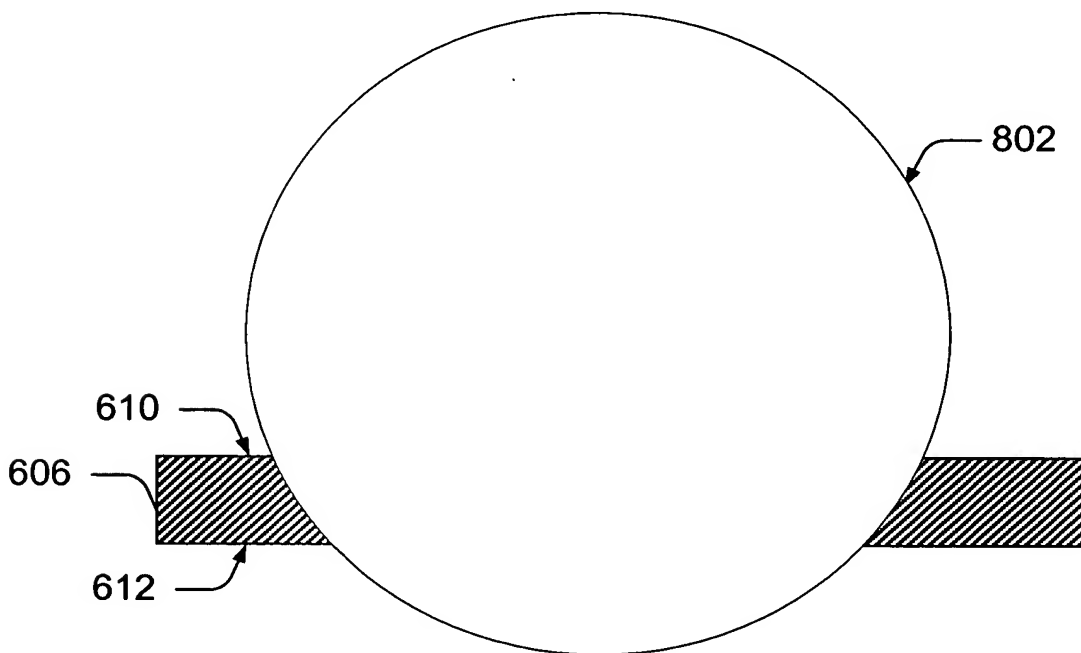


Fig. 11b

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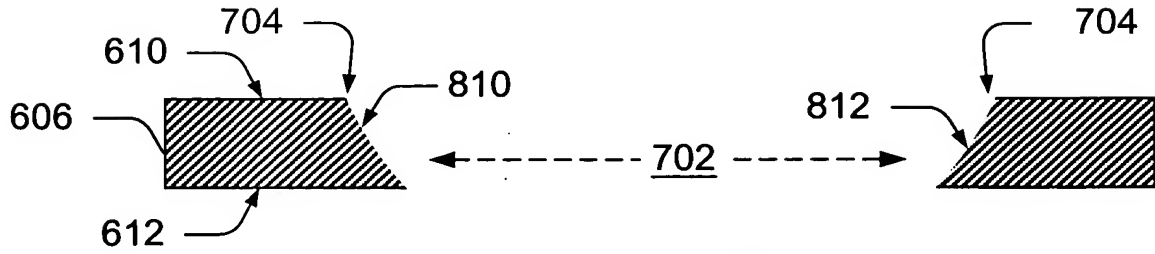


Fig. 11c

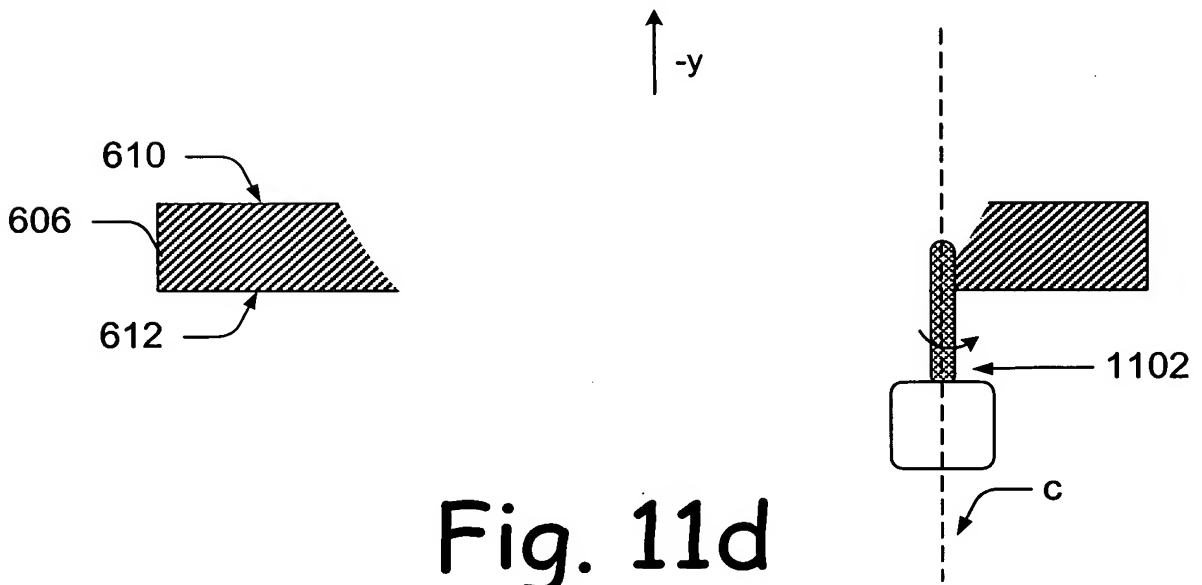


Fig. 11d

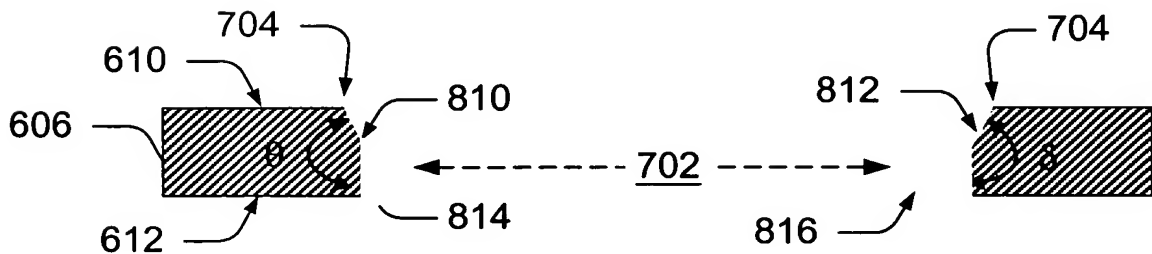


Fig. 11e

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